

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16174
1.3 Title of PCN	TSHT(China) additional LQFP7x7 48L package assembly line for STM32G0Bx/G0Cx listed products
1.4 Product Category	STM32G0B0x, STM32G0B1x, STM32G0C1x
1.5 Issue date	2026-09-07

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	TSHT (China)

4. Description of change

	Old	New
4.1 Description	Current Wire bonding material: - JSCC (China) Gold wire or copper wire	Current Wire bonding material: - JSCC (China) Gold wire or copper wire Added Wire bonding material : - TSHT(China) Copper Palladium wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change - no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose Microcontroller sub-group decided to extend the capacity through an already qualified back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2026-12-16
7.2 Intended start of delivery	2027-01-08
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16174 MDRF-GPAM-RER2501 PCN16174_TSHT(China) addnl LQFP7x7 48L pck STM32G0Bx-G0Cx PLAN .pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-09-07

9. Attachments (additional documentations)
16174 Public product.pdf 16174 MDRF-GPAM-RER2501 PCN16174_TSHT(China) addnl LQFP7x7 48L pck STM32G0Bx-G0Cx PLAN .pdf 16174 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32G0B0CET6	
	STM32G0B0CET6TR	
	STM32G0B1CBT3	
	STM32G0B1CBT6	
	STM32G0B1CCT6	
	STM32G0B1CCT6TR	
	STM32G0B1CET6	
	STM32G0C1CET6	

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